Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	793	wafer same solder\$4 same ((flip\$ or chip\$4 or bond\$4) and adhesive)	US-PGPUB; USPAT	OR	OFF	2005/11/16 14:41
L2	84	wafer same solder\$4 same ((flip\$ with chip\$4 with bond\$4) and adhesive)	US-PGPUB; USPAT	OR	OFF	2005/11/16 14:41
L3	58	wafer\$4 same solder\$4 same (reflect\$4 or mirror\$4) same electrod\$4	US-PGPUB; USPAT	OR	OFF	2005/11/16 14:56
L4	36	(wafer\$4 same microstructu\$4 same electrod\$4 same (mirror\$4 or reflect\$4))	US-PGPUB; USPAT	OR	OFF	2005/11/16 14:57
L5	28	(wafer\$4 same electrod\$4 same (mirror\$4 or reflect\$4)) and solder\$4 and 385/16-18.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/16 14:58
S1	47	wafer\$4 same solder\$4 same (reflect\$4 or mirror\$4) same electrod\$4	US-PGPUB; USPAT	OR	OFF	2005/11/16 14:56
S2	0	(wafer\$4 same microsctructu\$4 same electrod\$4) and 385/16-18. ccls.	US-PGPUB; USPAT	OR	OFF	2005/05/27 07:53
S3	2	(wafer\$4 same microstructu\$4 same electrod\$4) and 385/16-18. ccls.	US-PGPUB; USPAT	OR	OFF	2005/05/27 07:54
S4	118	(wafer\$4 same microstructu\$4 same electrod\$4)	US-PGPUB; USPAT	OR	OFF	2005/05/27 07:55
S5	22	(wafer\$4 same microstructu\$4 same electrod\$4 same (mirror\$4 or reflect\$4))	US-PGPUB; USPAT	OR	OFF	2005/11/16 14:57
S6	2045	(wafer\$4 same electrod\$4 same (mirror\$4 or reflect\$4))	US-PGPUB; USPAT	OR	OFF	2005/05/27 12:58
S7	81	S6 and 385/16-18.ccls.	US-PGPUB; USPAT	OR ·	OFF	2005/05/27 08:00
S 8	80	S7 not S5	US-PGPUB; USPAT	OR	OFF	2005/05/27 12:57
S9	144719	"8" and solder\$4	US-PGPUB; USPAT	OR	OFF	2005/05/27 12:57
S10	23	(wafer\$4 same electrod\$4 same (mirror\$4 or reflect\$4)) and solder\$4 and 385/16-18.ccls.	US-PGPUB; USPAT	OR	OFF	2005/11/16 14:57